

End-metallization dippers



LGTM-6100 series

- Low cost per dipped component
- Dipping accuracy 10 microns
- Suited for high volume production
- For 0201 up to 2520 chip sizes
- Capacity up to 800.000 pieces per hour



End metallization dipper

Designed for dipping of end terminals on surface mount components. The special design assures a flexible dipping process with a high production capacity and high quality terminations. The programmable dipping parameters allow optimization of the paste deposition and reduction of defects. Optional tooling for loading and unloading of components is available for manual and fully automated production.

Technical specification:

Paste thickness: +/- 10 microns

Dipping head positioning: +/- 2 microns

Ink tray flatness: +/- 5 microns

HMI: Color touch screen

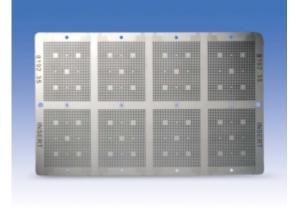
Fully programmable dipping process

Vacuum: 650mm Hg Air pressure: 0.5 MPa

Size: 1200 x 1000 x 1950mm Weight: 700kg (manual loading)

Thin Carrier Plates

- Superior dipping results
- Round or diamond shaped holes
- Fast heating and cooling during drying
- Allows two sided dipping
- Very low tooling cost



The unique Thin Carrier Plate assures a high chip holding force with high centering accuracy. The thin carrier plate requires very low energy consumption during the drying process because of the low thickness and material choice. With an unparalleled number of chips per plate the dipping process is extremely efficient.

Technical specification:

Holes: 496 -18.128 /plate

2 side dip: >0603

Chip sizes: 0201 - 2520

Other chip sizes on request

Hole precision: ±10 microns

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